



Material Content Data Sheet



Sales Product Name		BSR316P H6327		Issued		19. July 2018		
MA#		MA001307980						
Package		PG-SC59-3-3		Weight*		13.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.009	0.06		624	
	noble metal	gold	7440-57-5	0.033	0.24		2419	
	inorganic material	silicon	7440-21-3	0.379	2.74	3.04	27415	30458
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		81	
	non noble metal	titanium	7440-32-6	0.006	0.04		405	
	non noble metal	chromium	7440-47-3	0.017	0.12		1214	
	non noble metal	copper	7440-50-8	5.564	40.29	40.46	402859	404559
wire	non noble metal	copper	7440-50-8	0.032	0.23	0.23	2309	2309
encapsulation	organic material	carbon black	1333-86-4	0.073	0.53		5316	
	plastics	epoxy resin	-	1.579	11.43		114297	
	inorganic material	silicondioxide	60676-86-0	5.690	41.21	53.17	412002	531615
leadfinish	non noble metal	tin	7440-31-5	0.261	1.89	1.89	18923	18923
plating	noble metal	silver	7440-22-4	0.168	1.21	1.21	12136	12136
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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